

ICS 31.030
CCS L90



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 48099-2026

Lid with preform for semiconductor packages

半导体封装用带预制焊环盖板

(English Translation)

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Foreword

GB/T 48099-2026 is a recommended national standard (GB/T) of the People's Republic of China, issued on 28 August 2026 by the State Administration for Market Regulation and the Standardization Administration of China, with effect from 1 March 2027.

It is under the responsibility of the Ministry of Industry and Information Technology (Electronics).

Classification: ICS 31.030; CCS L90.

1 Scope

This standard concerns lids with a preformed solder ring, used for sealing semiconductor packages. Such lids are supplied with solder already in place, so that a package can be closed in a controlled soldering step.

The document will matter to producers of package lids and sealing components, manufacturers of semiconductor packages, device makers who buy lids and need agreed product definitions, and incoming-inspection or testing laboratories. It is particularly of interest to suppliers serving the electronics components industry, where lids and packages are bought and specified separately from the devices they enclose. It is a recommended (voluntary) national standard taking effect on 1 March 2027, prepared under the Ministry of Industry and Information Technology. A shared definition of the lid and its solder preform helps buyers and suppliers agree on what is delivered before assembly begins.